

AIDA - Academia meets Industry: Advanced interconnections for chip packaging in future detectors

Tuesday, 9 April 2013

Frontiers in Interconnections (12:40 - 13:20)

-Conveners: Michael Campbell

time	[id] title	presenter
12:40	[39] Shrinking 3D ICs - Capabilities and Frontiers of Through Silicon Via Technologies	KLUMPP, Armin
13:00	[56] Unconventional fabrication approaches create opportunities for 3D integration	FISCHER, Andreas